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LASER-INDUCED CUTTING OF METAL INTERCONNECT

Abstract of the Disclosure

An electrical interconnect includes a substrate having an insulating surface upon which is placed an electrically-
5 conductive cut-link pad and a pair of electrically-
conductive lines. The lines are bonded to the cut-link pad and are substantially more resistant to heat flow per unit length than is the cut-link pad. In a preferred
embodiment, the thermal resistance per unit length of the
10 cut-link pad is lowered by designing the pad such that its width is greater than the width of either of the lines. A method for cutting a circuit includes directing a laser upon the cut-link pad of an interconnect, as described above. The laser is maintained upon the pad until the cut-
15 link pad is ablated, severing the circuit.